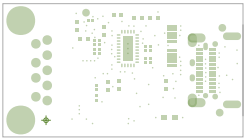
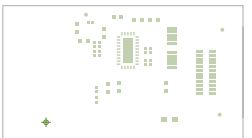
ART FILM - smt



CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION SOLDERMASK TOP		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 7 OF 13

ART FILM - smt

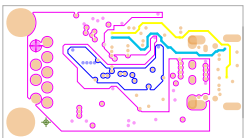
ART FILM - spt



CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION PASTEMASK TOP		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 11 OF 13

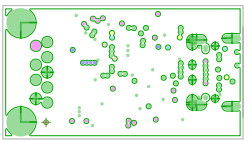
ART FILM - spt

ART FILM - ly4

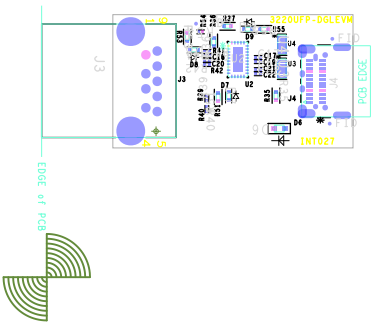


CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION LAYER 4 - PWR		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 4 OF 13

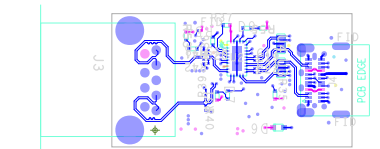
ART FILM - ly4



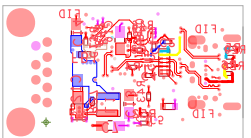
CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION **LAYER 5 - GND**		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH **5** OF 13



CUSTOMER NAME TI			ASSMBLY TOP	
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design			DESCRIPTION SILKSCREEN TOP	
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 9 OF 13

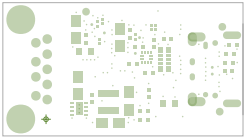


CUSTOMER NAME TI			ASSMBLY TOP	
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION LAYER 1 - TOP		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 1 OF 13



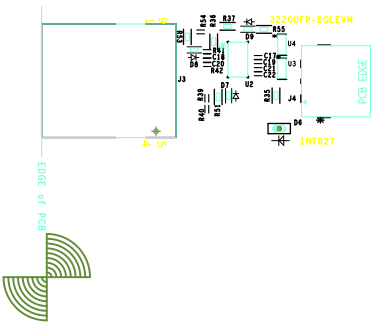
CUSTOMER NAME TI				ASSEMBLY BOTTOM	
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design			DESCRIPTION LAYER 6 - BOTTOM		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 6	OF 13

ART FILM - smb



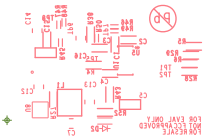
CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION SOLDERMASK BOTTOM		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 8 OF 13

ART FILM - smb



CUSTOMER NAME TI			ASSMBLY TOP	
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design			DESCRIPTION SILKSCREEN TOP	
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 9 OF 13

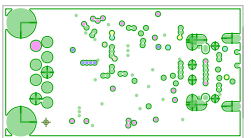
ART FILM - ssb



CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION SILKSCREEN BOTTOM		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 10 OF 13

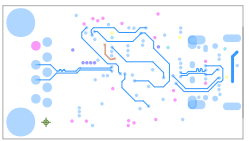
ART FILM - ssb

ART FILM - ly2

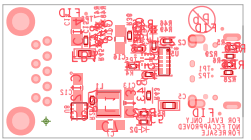


CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION LAYER 2 - GND		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 2 OF 13

ART FILM - ly2

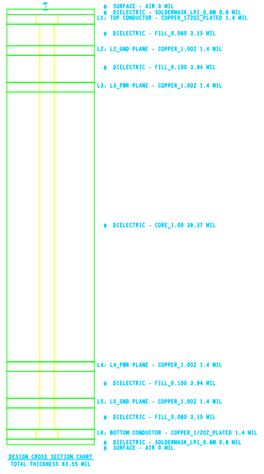


CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION LAYER 3 - SIGNAL		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 3 OF 13



CUSTOMER NAME TI				ASSEMBLY BOTTOM
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design			DESCRIPTION SILKSCREEN BOTTOM	
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 10 OF 13

ART FILM - fab



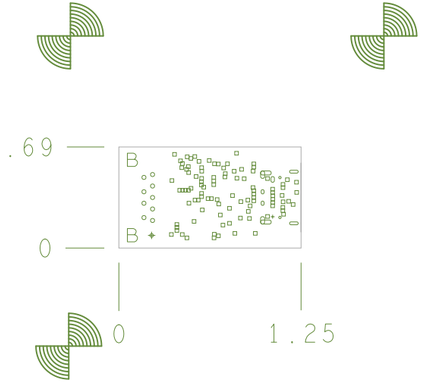
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
B	91.0	+3.0/-3.0	PLATED	2
◦	28.0	+3.0/-3.0	PLATED	9
◦	17.72	+3.15/-3.15	PLATED	2
□	8.0	+3.0/-8.0	PLATED	100
+	27.56	+3.0/-3.94	NON-PLATED	1
▭	72.83x27.56	+3.15/-3.15	PLATED	2
▭	59.06x19.69	+3.15/-3.15	PLATED	2
◊	51.18x27.56	+3.15/-3.15	PLATED	2
◦	29.53x19.69	+3.15/-3.15	PLATED	2
◦	39.37x23.62	+3.0/-3.94	NON-PLATED	1

CONTROLLED IMPEDANCE DESIGN

ALL 4.8 MIL LINES ON ALL LAYERS
SHALL BE 50 OHM SINGLE ENDED IMPEDANCE +/-10%

ALL 4.5 MIL LINES WITH 5.5 MIL SPACED ON LAYERS 1,3 AND 6
SHALL BE 90 OHM DIFFERENTIAL IMPEDANCE +/-10%

STACK-UP	MINIMUM COPPER WEIGHT
LY1-SIGNAL	1/2 oz
LY2-GND PLANE	1 oz
LY3-SIGNAL	1/2 oz
LY4-PWR PLANE	1/2 oz
LY5-GND PLANE	1 oz
LY6-SIGNAL	1/2 oz



FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

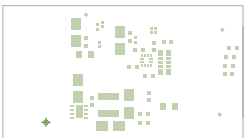
PROCESS NOTES:

1. PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD. NICKEL 100 MIN MICROINCHES THK GOLD 2-6 MICROINCHES THK.
2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: BLACK. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
3. FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

CUSTOMER NAME	TI			
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design			DESCRIPTION FABRICATION DRAWING	
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 13 OF 13

ART FILM - fab

ART FILM - spb



CUSTOMER NAME TI				
BOARD NAME TIDA-00891 USB Type-C TM Plug to USB Type-A Receptacle SS MUX with UFP Controller Reference Design		DESCRIPTION PASTEMASK BOTTOM		
BOARD NO.	REV A1	DATE 13 NOV 2015	PRJ# TIDA-00891	SH 12 OF 13

ART FILM - spb

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